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Texas Instruments New Product Update

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- Please post questions in the chat or contact your TI sales contact or field applications engineer



OPAX310: A 2-IN-1 AMPLIFIER TO IMPROVE YOUR APPLICATION'S DRIVE STRENGTH OR LOWER POWER CONSUMPTION

New Product Update

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– Systems Engineer

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– Applications Engineer

Agenda

- Device Introduction
- Product Highlight 1 & Applications
- Product Highlight 2 & Applications
- How to get started with OPAx310

Please feel free to “chat” Bhuvanesh R K, Systems Engineer or Robert Clifton, Applications Engineer, who will be available to answer any questions you have throughout this presentation.

OPAx310: OPA310 / OPA2310 / OPA4310

1.5V – 5.5V Operation | 3 MHz | RRIO | High Output Current, Fast Enable Amplifier

Features

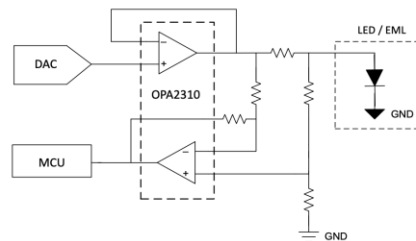
- **High Output Current**
- **Fast Enable**
- **Fail-Safe Input Structure**
- Low Offset over temp 1.4 mV (max)
- Gain Bandwidth 3 MHz (typ)
- Quiescent Current 165 μ A (typ)
- Low Noise 13 nV/ $\sqrt{\text{Hz}}$ @10KHz (typ)
- Supply Voltage 1.5 V to 5.5 V
- **Small Size, PowerPAD Pkgs with Thermal Protection**

Benefits

- High output current helps easily bias Laser diodes, LEDs, photo diodes and drive audio pre-amplifiers, small speaker
- Low offset and Low Noise enables precision current, voltage sensing and use in signal chain applications
- EMI Filtered, Fail safe inputs with 8kV HBM ESD along with built in Power on reset ensures robust performance
- Stable across wide range of capacitive, resistive loads
- Excellent shutdown function with fast enable time for low power

Applications

- Optical Module Laser Drivers and LED Drivers
- Discrete Howland Current Pumps
- DAC Buffers & Reference Buffers
- Low-Power, High-Performance Applications
- Building Automation, Portable Electronics / Medical



LED / EML Biasing With Current Sense

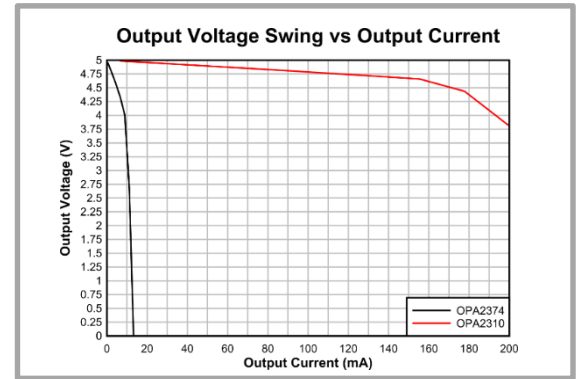
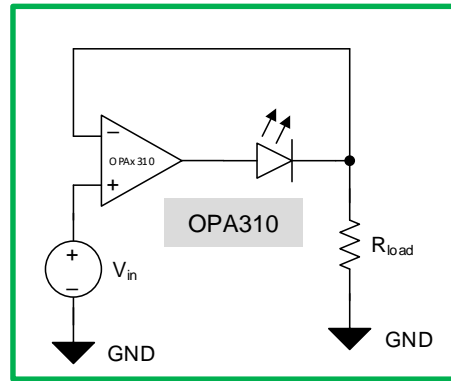
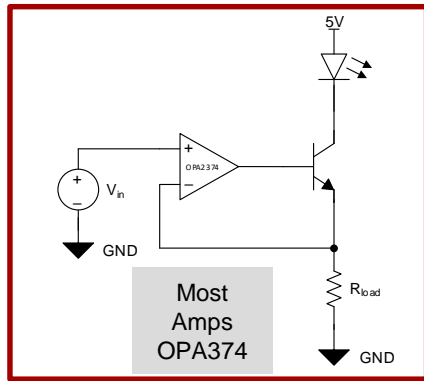


High output current applications

Improve drive strength

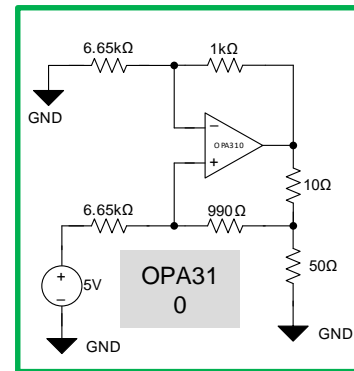
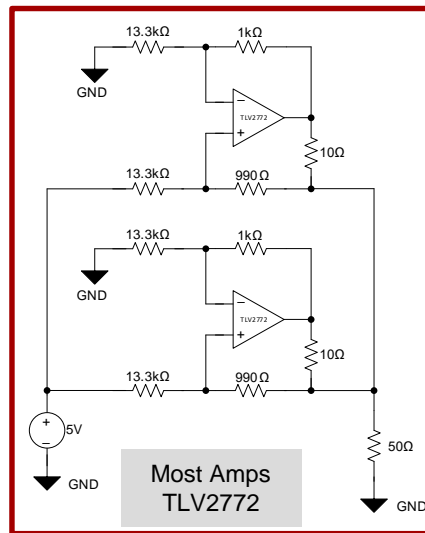
LED | Laser driver

- Many amps require an external transistor to properly drive the LED / Laser because of,
 - Limited output current at lower supply voltages
 - Limited output swing when directly driving the LED
- Example amp (OPAx374) has output voltage swing that is heavily limited even at a typical LED current of $\pm 10\text{mA}$ requiring additional & external FET / BJT
- The OPAx310 **can drive directly various LEDs / Lasers** even at lower supply voltages with better output swing **without additional external transistor**, saving board area and cost.



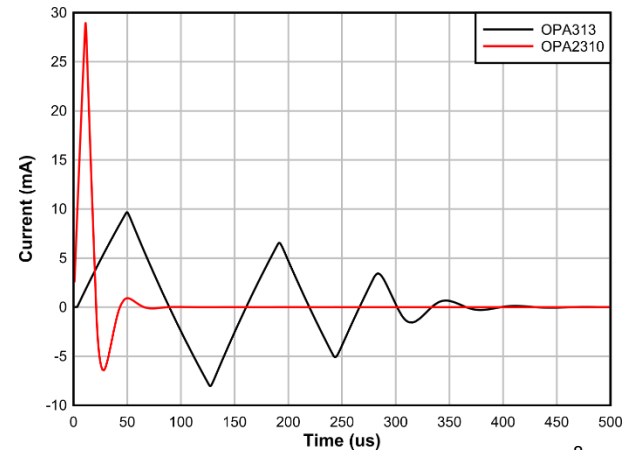
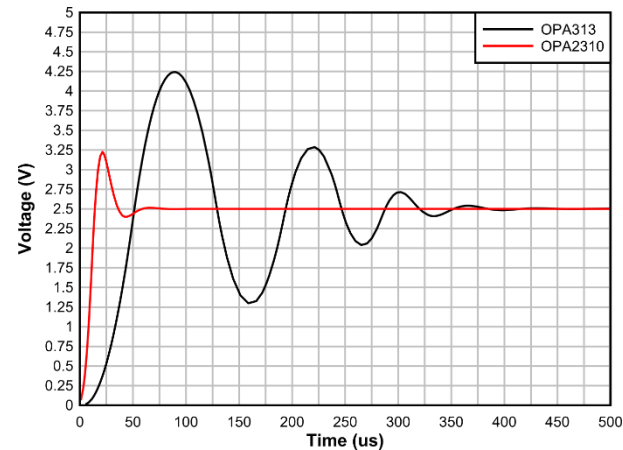
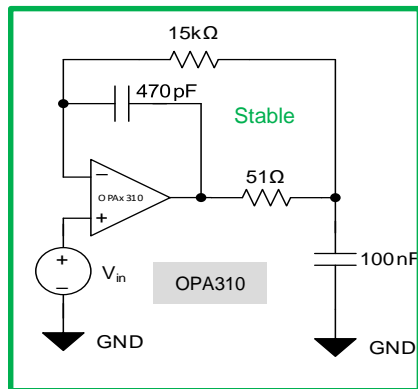
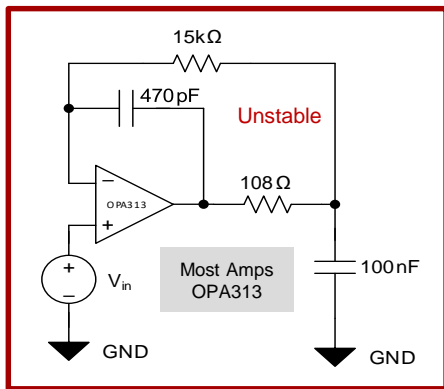
Howland current pump

- For building current sources, higher output current amplifier helps **reduce the need for higher channel count** to drive the same load (with better voltage compliance)
- In this example, a 50Ω load requires 75mA of current (4.5V at the amplifier output \rightarrow 1V Headroom at Supply voltage of 5V)
 - Most amps require two channels in parallel**
 - Single amp of OPAx310 drives this load
- OPAx310 Solution Benefits:**
 - Saves cost : Cheaper
 - Saves board area : Smaller



Reference buffer | shield amplifiers

- Amplifiers can struggle when driving large value capacitors that can experience switching voltage or current transients
 - These transients drive amp **into current limit (non-linear operation)** when used as reference buffers or guard / shield amps
- With OPA310's high output current & fast slew rate the application can have:
 - **Linear operation (does not enter current limiting)**
 - Less overshoot & **Faster settling time**



Electrical characteristics | Drive strength

1. Tested Swing with 50mA :

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
A _{OL}	Open-loop voltage gain ⁽⁶⁾	V _S = 3.3 V, (V ₋) + 0.25 V < V _O < (V ₊) – 0.25 V, I _L = ±50 mA	T _A = 25°C	80	102		dB

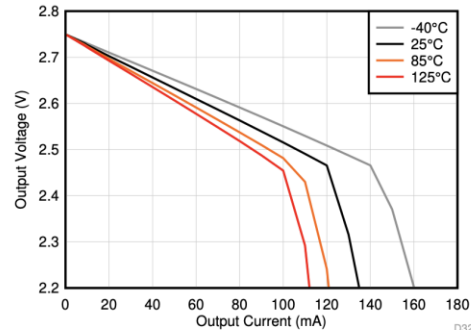
2. Short Circuit Current :

- 5.5V Supply : 110-mA (minimum) and 150-mA (typical)
- 1.8V Supply : 6-mA (minimum over temp) and 20-mA (typical)

3. Voltage Swing Closer to Rails :

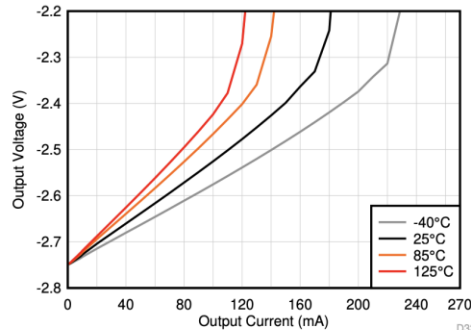
V_{OH}	Voltage output swing from positive rail	$V_S = 1.8\text{ V}$, $R_L = 2\text{ k}\Omega$ to $V_S / 2$			10	21	mV
		$V_S = 1.8\text{ V}$, $R_L = 10\text{ k}\Omega$ to $V_S / 2$			2	11	
		$V_S = 1.8\text{ V}$, $R_L = 2\text{ k}\Omega$ to $V_S / 2$	$T_A = -40^\circ\text{C}$ to 125°C			51	
		$V_S = 1.8\text{ V}$, $R_L = 10\text{ k}\Omega$ to $V_S / 2$	$T_A = -40^\circ\text{C}$ to 125°C			26	
		$V_S = 5.5\text{ V}$, $R_L = 2\text{ k}\Omega$ to $V_S / 2$			3.5	20	
		$V_S = 5.5\text{ V}$, $R_L = 10\text{ k}\Omega$ to $V_S / 2$			0.75	9	
		$V_S = 5.5\text{ V}$, $R_L = 2\text{ k}\Omega$ to $V_S / 2$	$T_A = -40^\circ\text{C}$ to 125°C			30	
		$V_S = 5.5\text{ V}$, $R_L = 10\text{ k}\Omega$ to $V_S / 2$	$T_A = -40^\circ\text{C}$ to 125°C			14	

Typical characteristic curves | Drive strength



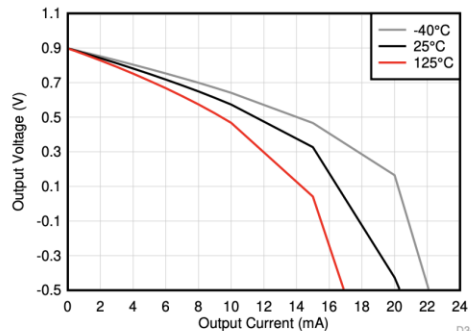
$V^+ = 2.75\text{ V}$, $V^- = -2.75\text{ V}$

Figure 7-21. Output Voltage Swing vs Output Current (Sourcing)



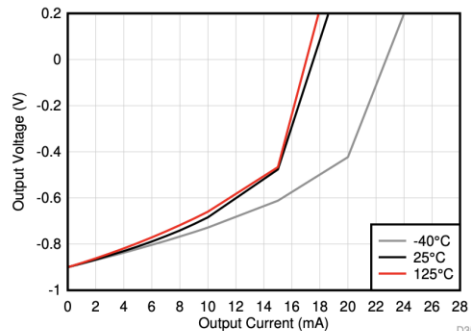
$V^+ = 2.75\text{ V}$, $V^- = -2.75\text{ V}$

Figure 7-22. Output Voltage Swing vs Output Current (Sinking)



$V^+ = 0.9\text{ V}$, $V^- = -0.9\text{ V}$

Figure 7-23. Output Voltage Swing vs Output Current (Sourcing)



$V^+ = 0.9\text{ V}$, $V^- = -0.9\text{ V}$

Figure 7-24. Output Voltage Swing vs Output Current (Sinking)

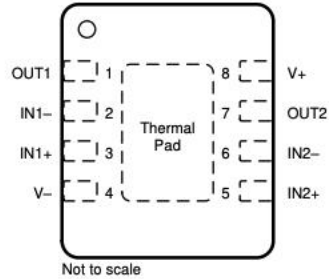
Enables much higher load currents at 5.5V

- $100\text{ mA } I_{\text{load}}$ with 0.3V to rails (typical)
- $-20\% I_{\text{load}}$ accounts for process variations

Enables greater output swing at lower supply voltages of 1.8V

- $5\text{ mA } I_{\text{load}}$ with 0.2V to rails (typical)
- $-20\% I_{\text{load}}$ accounts for process variations

OPAx310 PowerPAD | Small size packages

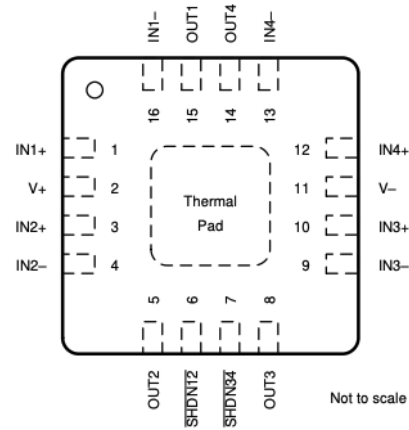


Connect exposed thermal pad to V-. See [Section 8.3.10](#) for more information.

**Figure 6-7. OPA2310 DSG Package
8-Pin WSON with Exposed Thermal Pad
(Top View)**

2CH : 2mm x 2mm

$R_{\theta JA} - 90.1\text{ }^{\circ}\text{C} / \text{W}$



Connect thermal pad to V-.

**Figure 6-12. OPA4310S RTE Package
16-Pin WQFN With Exposed Thermal Pad
(Top View)**

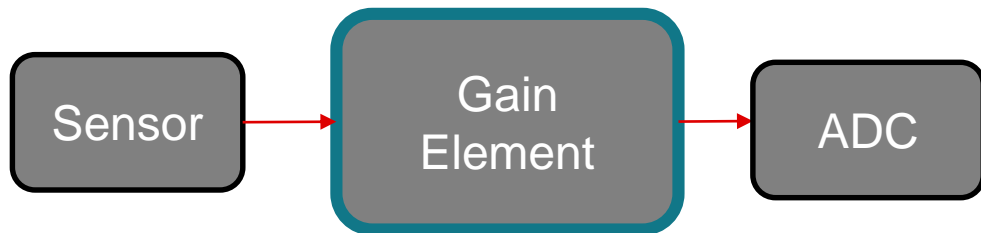
4CH : 3mm x 3mm

$R_{\theta JA} - 57.6\text{ }^{\circ}\text{C} / \text{W}$

Lower power consumption

How to lower power consumption

- Typical amplifier signal chain consists of Sensor / Gain Element / ADC



- Sensors have longer latency and are usually left on
- ADC can be operated in burst mode to save power
- How to reduce amplifier power ?

Use case for fast shutdown

- Straight forward way to reduce amp power is to use low power amp

Amplifier	Quiescent Current when powered-on (nA)	Bandwidth (kHz)	Noise at 10kHz (nV/rt-Hz)	Output Impedance at 10kHz (Ohms)
TLV8541	500	8	264	8000
TLV379	1000	90	83	28000
TLV9041	10000	350	65	7500

Disadvantages : Lower bandwidth, Higher Noise, Hard to stabilize

- **Better Approach: Use fast enable amplifier with better performance & turn off amplifier when not in use to lower power**
 - Turn on amplifier just before ADC conversion start with enough time to account for enable time & settling time. *OPAx310 is optimized for faster settling after enable*
 - Example in the next slide comparing average power in 1ms for OPAx310 vs Other Amps

Use case for fast shutdown

OPAx310 achieves **lowest duty cycle** for 1ms example with fast enable & settling

Amplifier	Enable time (μs)	Settling time 0.01% (μs)	Total ON time over 1ms (μs)	Total SHDN time over 1ms (μs)	Minimum Duty Cycle D (%)
TLV9041	160	30	190	810	19
TLV9001	70	3	73	927	7.3
TLV9061	10	1	11	989	1.1
OPA310	1	1.6	$2.6 = (1 + 1.6)$	$997.4 = (1000 - 2.6)$	$0.26 = (2.6 / 1000)$

OPAx310 consumes **lowest current in shutdown** while providing faster enable time

Amplifier	Bandwidth (MHz)	Enable time (μs)	Quiescent Current when powered-on Q_ON (μA)	Quiescent Current in shut down Q_OFF (μA)
TLV9041	0.35	160	10	0.750
TLV9001	1	70	60	0.500
TLV9061	10	10	538	0.500
OPA310	3	1	165	0.265

1ms average quiescent current vs performance

Type	Amplifier	Average Quiescent current in 1ms (μ A)	Thermal noise floor (nV/rt-Hz)	Output Impedance at 10 kHz (Ohms)
Always ON	TLV8541	0.50	264	8000
ON / OFF	TLV9041	1.96	65	7500
ON / OFF	TLV9001	4.84	27	1200
ON / OFF	TLV9061	6.41	10	100
ON / OFF	OPA310	0.69 ($165 \cdot 0.0026 + 0.265 \cdot 0.9974$)	13	1000

OPAx310 enables duty cycling to achieve good power-performance balance,

➤ Lower Noise

➤ Better Stability

➤ Lower Power

Electrical characteristics | Shutdown response

Fast Enable Time:

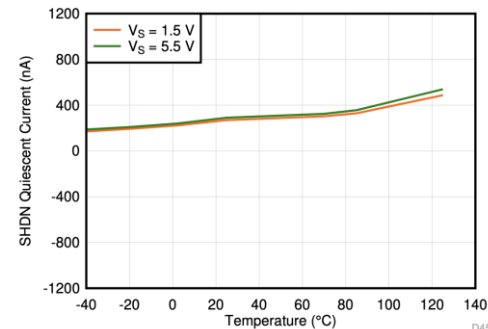
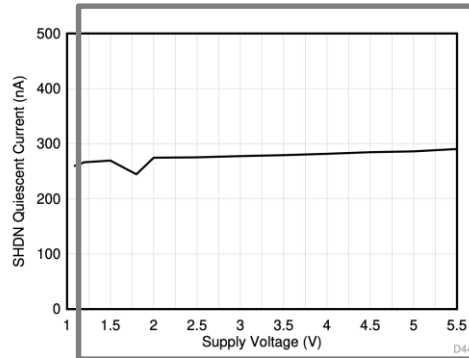
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{ON}	Amplifier enable time (full shutdown) (7) (1)	$G = +1$, $V_{CM} = V_S / 2$, $V_O = 0.9 \times V_S / 2$, R_L connected to V_-		1	1.6	μs
t_{OFF}	Amplifier disable time (7)	$G = +1$, $V_{CM} = V_S / 2$, $V_O = 0.1 \times V_S / 2$, R_L connected to V_-		1		μs

Lower Shutdown Quiescent Current:

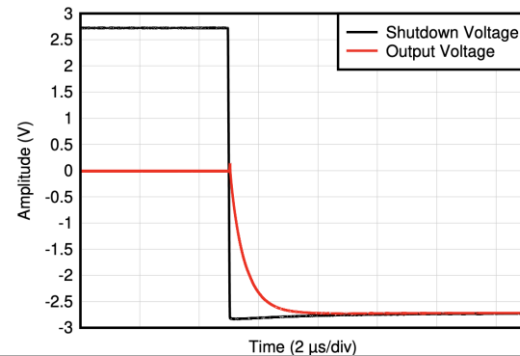
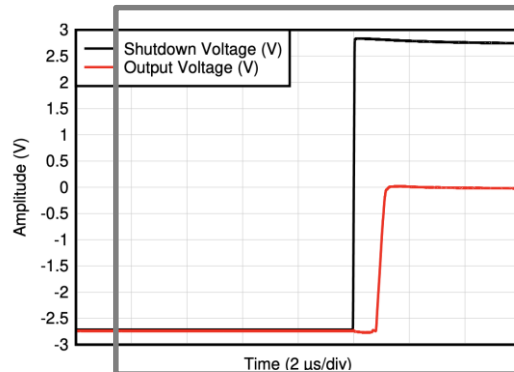
I_{Q_SHDN}	Shutdown current per amplifier	All amplifiers disabled, $\overline{SHDN} = V_-$, OPA4310S	0.100	0.150	μA
		All amplifiers disabled, $\overline{SHDN} = V_-$, OPA310S	0.265	0.475	μA
I_{Q_SHDN}	Shutdown current per amplifier	All amplifiers disabled, $\overline{SHDN} = V_-$, OPA2310S	0.200	0.375	μA
I_{Q_SHDN}	Shutdown current per amplifier (1)	All amplifiers disabled, $\overline{SHDN} = V_-$, $T_A = -40^\circ C$ to $85^\circ C$, OPA4310S		0.300	μA
		All amplifiers disabled, $\overline{SHDN} = V_-$, $T_A = -40^\circ C$ to $85^\circ C$, OPA310S		0.700	μA
I_{Q_SHDN}	Shutdown current per amplifier (1)	All amplifiers disabled, $\overline{SHDN} = V_-$, $T_A = -40^\circ C$ to $85^\circ C$, OPA2310S		0.600	μA
Z_{OUT_SHDN}	Output impedance during shutdown	Amplifier disabled	43 11.5		G pF

Typical characteristics | Shutdown response

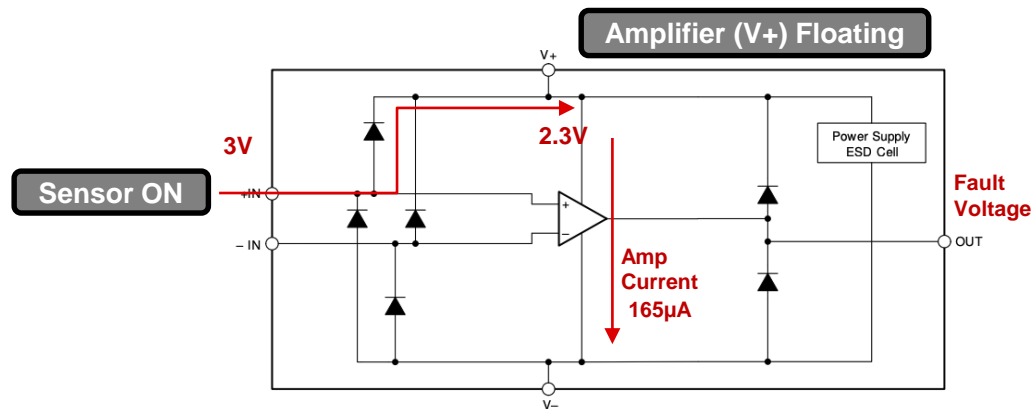
SHDN Quiescent Current, 1CH



Enable / Disable Response



Problem scenario | Why fail safe ESD ?



Fault Scenarios

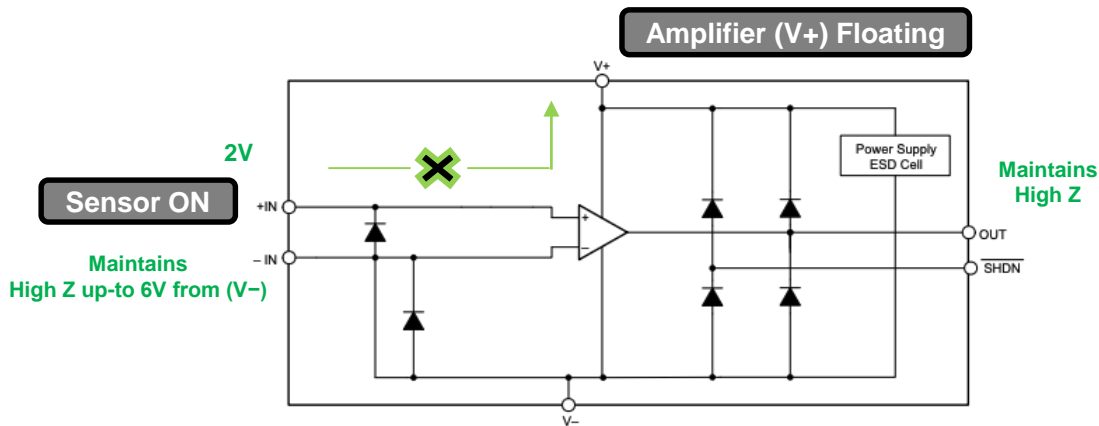
- ☐ Separate power supplies between Amp & Sensor
- ☐ Power Sequencing

Most Amps : ESD diodes to V+

Fault Scenarios if Sensor output voltage is present before amplifier supply voltage

Amplifier “back-powering”, sensor loading & fault signal at output

OPAx310 fail safe ESD



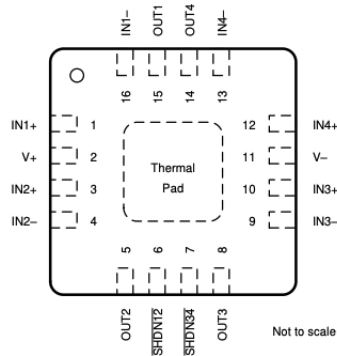
Robust Performance

- ❑ 8kV ESD HBM
- ❑ Fail-safe ESD Inputs

OPAx310 uses modified ESD Structure with No ESD diodes to V+ rails

- **No Sensor Loading** : Maintains High Z at inputs up to 6V from (V-)
- **No Back Powering & Output Faults** to ADC / Microcontroller

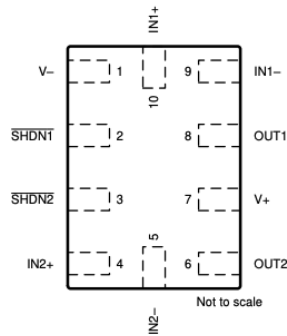
OPAx310S shutdown packages



Connect thermal pad to V-.

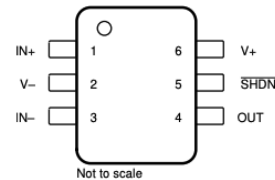
**Figure 6-12. OPA4310S RTE Package
16-Pin WQFN With Exposed Thermal Pad
(Top View)**

4CH : 3mm x 3mm



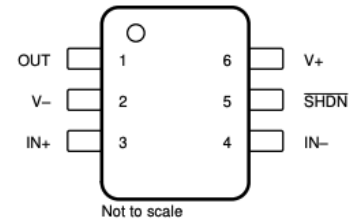
**Figure 6-8. OPA2310S RUG Package
10-Pin X2QFN
(Top View)**

2CH : 2mm x 1.5mm



**Figure 6-5. OPA310S DCK Package
6-Pin SC70
(Top View)**

1CH : 2mm x 1.25mm



**Figure 6-4. OPA310S DBV Package
6-Pin SOT-23
(Top View)**

1CH : 2.9mm x 1.6mm

Getting started

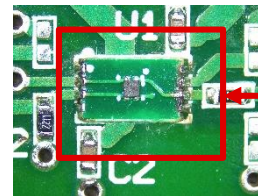
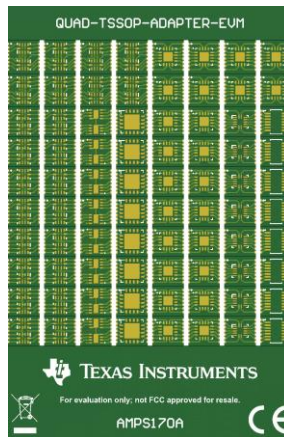
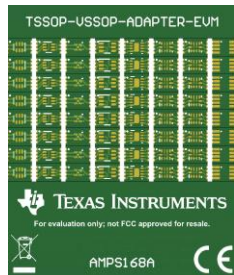
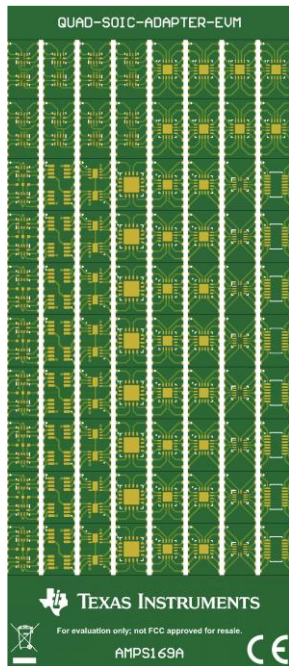
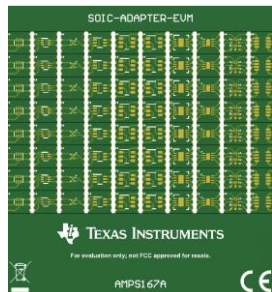
You can start evaluating this device leveraging the following:

Content type	Content title	Link to content or more details
Product folder	OPAx310 product folder	https://www.ti.com/product/OPA310 https://www.ti.com/product/OPA4310 https://www.ti.com/product/OPA2310
Samples	Sampling page for OPA310, OPA2310, OPA4310	https://www.ti.com/product/OPA310#order-quality https://www.ti.com/product/OPA4310#order-quality https://www.ti.com/product/OPA2310#order-quality
Technical blog content or white paper	Various articles: <ul style="list-style-type: none">• Op Amp ESD Protection Structures• Analysis of Improved Howland Current Pump• Fast Enable Amplifier with Fail Safe Input ESD• Benefits of Op-Amps with High Output Current	https://www.ti.com/lit/pdf/slvaex7 https://www.ti.com/lit/pdf/sboa437 To be published soon To be published soon
Selection and design tools and models	Spice models with Reference Design	https://www.ti.com/lit/tsc/sbomc55
Development tool or evaluation kit	SMALL-AMP-DIP-EVM evaluation module SURFACE-MOUNT-ADAPTER-EVM	https://www.ti.com/tool/SMALL-AMP-DIP-EVM https://www.ti.com/tool/SURFACE-MOUNT-ADAPTER-EVM

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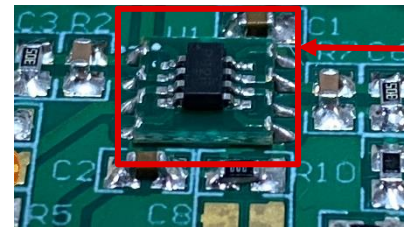
The Four Board Variants



TSSOP to X2SON

Features:

- Four boards to choose from: SOIC-8, TSSOP-8/VSSOP-8, SOIC-14/16, and TSSOP-14/16
 - Examples: SOT-23, X2SON, WSON, etc.
- Optimized PCB designed to reduce parasitics
- PCB layout can be referenced for dual footprint designs
- Allow customer to evaluate devices in their system when specific package is not available
- Help transition from larger packages to new small modern ones



SOIC to SOT-23



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